

Attorney's Docket No.: 07402-039001

**OFFICIAL COMMUNICATION****FACSIMILE****FOR THE PERSONAL ATTENTION OF:  
EXAMINER LOURDES CRUZ****GROUP 2815 FAX NO: (703) 872-9319****FAX COPY RECEIVED**

Number of pages including this page 11

OCT 07 2002

TECHNOLOGY CENTER 2800

Applicant : Carlson, et al.

Art Unit : 2815

Serial No. : 09/547,061

Examiner : Lourdes Cruz

Filed : April 7, 2000

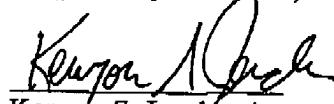
Confirmation No. : 3231

Title : INSULATOR/METAL BONDING ISLAND FOR ACTIVE AREA SILVER  
EPOXY BONDING**FACSIMILE COMMUNICATION****Box AF**Commissioner for Patents  
Washington, D.C. 20231

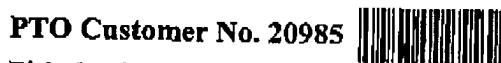
Sir:

Attached to this facsimile communication cover sheet is a Response and Notice of Appeal, faxed this 7<sup>th</sup> day of October, 2002, to Group 2815, the United States Patent and Trademark Office.

Respectfully submitted,

  
\_\_\_\_\_  
Kenyon S. Jenckes / smr  
Reg. No. 41,873

Date: October 7, 2002



PTO Customer No. 20985

Fish & Richardson P.C.  
4350 La Jolla Village Drive, Suite 500  
San Diego, California 92122  
Telephone: (858) 678-5070  
Fax: (858) 678-5099

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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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 SILVER EPOXY BONDING

BOX AF

Commissioner for Patents  
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RESPONSE

In response to the action mailed June 6, 2002, please amend the application as follows:

In the claims:

Please cancel claims 14-17.

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Please amend claims 1, 5, and 9 as follows:

TECHNOLOGY CENTER 2800

-- 1. (Twice Amended) A semiconductor interconnection system, comprising:

a semiconductor die;  
 first and second conductive contacts, said first conductive contact coupled to a surface of said semiconductor die, and said second conductive contact coupled to an external structure;

a silver epoxy bond interposed between said first and second conductive contacts, said epoxy bond providing

## CERTIFICATE OF TRANSMISSION BY FACSIMILE

I hereby certify that this correspondence is being transmitted by facsimile to the Patent and Trademark Office on the date indicated below.

October 7, 2002  
 Date of Transmission

Susan Regan  
 Signature

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